



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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OCT 10 2003

TC 1700

*In re* Application of  
Khaselev *et al.*

Serial No.: 10/050,013

Filing Date: January 17, 2002

For: ELECTROPLATING SOLUTION FOR HIGH  
SPEED PLATING OF TIN-BISMUTH SOLDER

Attorney Docket No. 13401-996

Examiner: E. Wong

Art Unit: 1753

Mail Stop: Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

#  
6/A  
W.M.  
10/15/03  
(N.R.)

**REPLY TO OFFICE ACTION UNDER 37 C.F.R. § 1.111**

SIR:

In response to Office Action mailed April 3, 2003, please enter the following amendments and remarks into the file of the above-captioned application. Amendments to the claims and specification are set forth below. Also attached is a formal version of Fig. 1 and a request for a three (3) month extension of time under 37 C.F.R. § 1.136 and fee authorization.